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This presentation contains forward-looking statements, including with respect to Intel's business plans and strategy, process and product roadmaps, and current and future technologies, as well as the anticipated benefits therefrom. Such statements involve many risks and uncertainties that could cause our actual results to differ materially from those expressed or implied, including: changes in demand for our products; changes in product mix; the complexity and fixed cost nature of our manufacturing operations; the high level of competition and rapid technological change in our industry; the significant upfront investments in R&D and our business, products, technologies, and manufacturing capabilities; vulnerability to new product development and manufacturing-related risks, including product defects or errata, particularly as we develop next generation products and implement next generation process technologies; risks associated with a highly complex global supply chain, including from disruptions, delays, trade tensions, or shortages; sales-related risks, including customer concentration and the use of distributors and other third parties; potential security vulnerabilities in our products; cybersecurity and privacy risks; investment and transaction risk; intellectual property risks and risks associated with litigation and regulatory proceedings; evolving regulatory and legal requirements across many jurisdictions; geopolitical and international trade conditions; our debt obligations; risks of large scale global operations; macroeconomic conditions; impacts of the COVID 19 or similar such pandemic; and other risks and uncertainties described in our earnings release dated July 27, 2023, our most recent Annual Report on Form 10-K and our other flings with the U.S. Securities and Exchange Commission. All information in this presentation reflects Intel management views as of the date hereof unless an earlier date is specified. Intel does not undertake, and expressly disclaims any duty, to update such statements, w

It Starts Here

intel® Innovation

Pat Gelsinger Intel CEO

> Starts Here

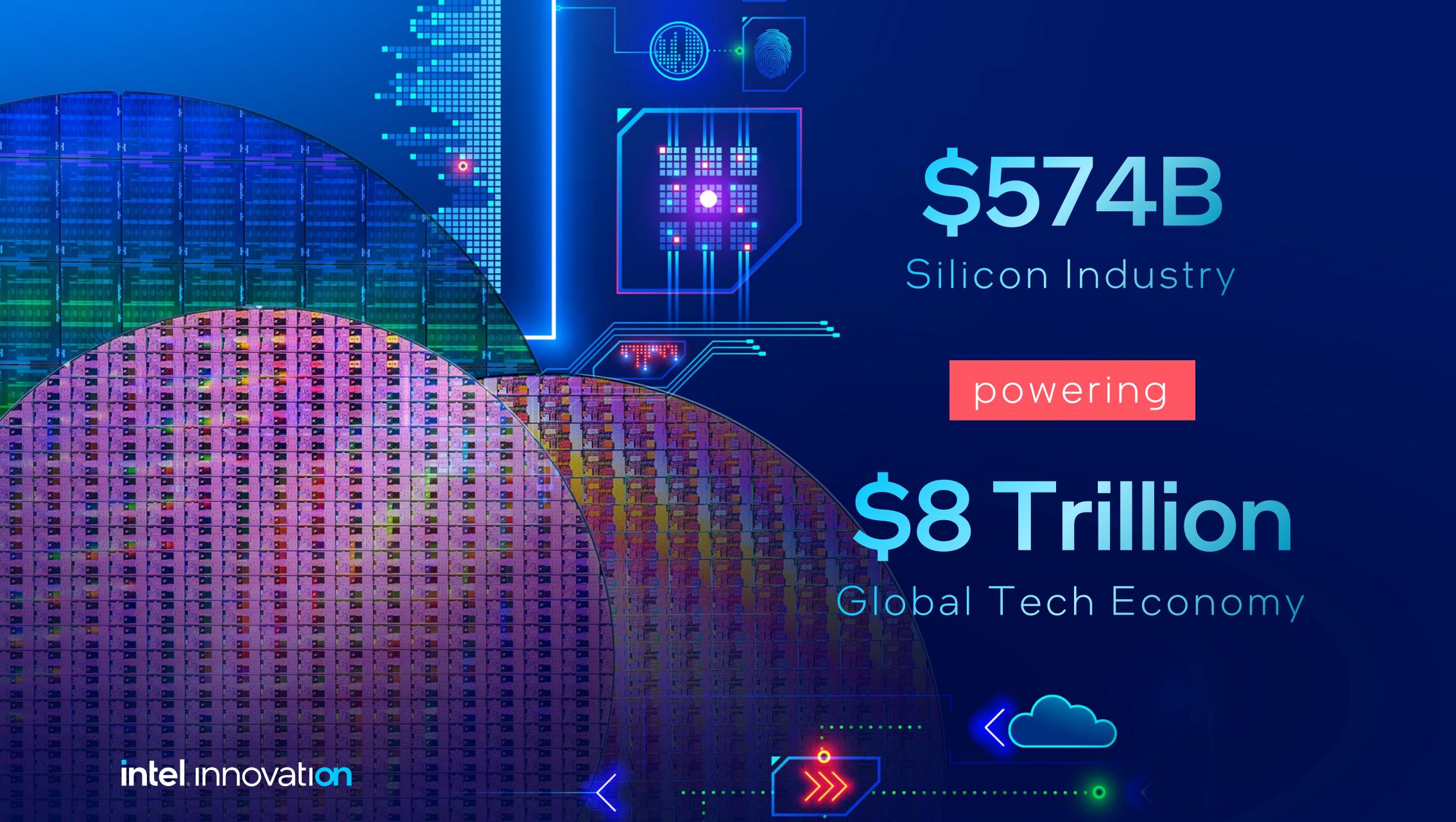






















Advanced Al capabilities toolkits



OpenVINO

Multiplatform systems and clusters









intel[®] Developer Cloud

cloud.intel.com

Available to all

cloud.intel.com

Intel-optimized Al Software

supported by the latest CPUs, NPUs and GPUs

1 week free

of Intel Developer Cloud access for every in-person attendee

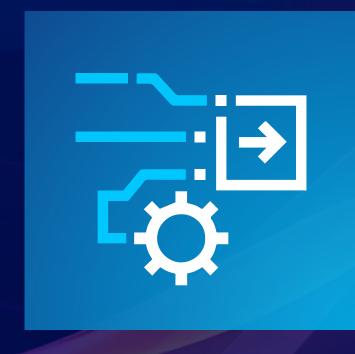
```
Starts
 Here
import webbrowser as siliconomy
accessibleDevelopment = "https://cloud.intel.com"
devNeeds = {"Open": True, "Choice": True,
         "Trust": True, "AI": True,
         "Client": True, "Edge": True,
         "Cloud": True }
if any(x is True for x in devNeeds.values()):
    siliconomy.open(accessibleDevelopment)
```

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Artificial Intelligence

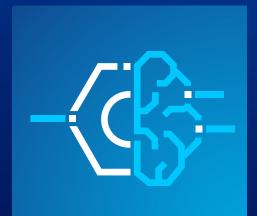


Next Generation Systems



Platforms and Edge to Cloud





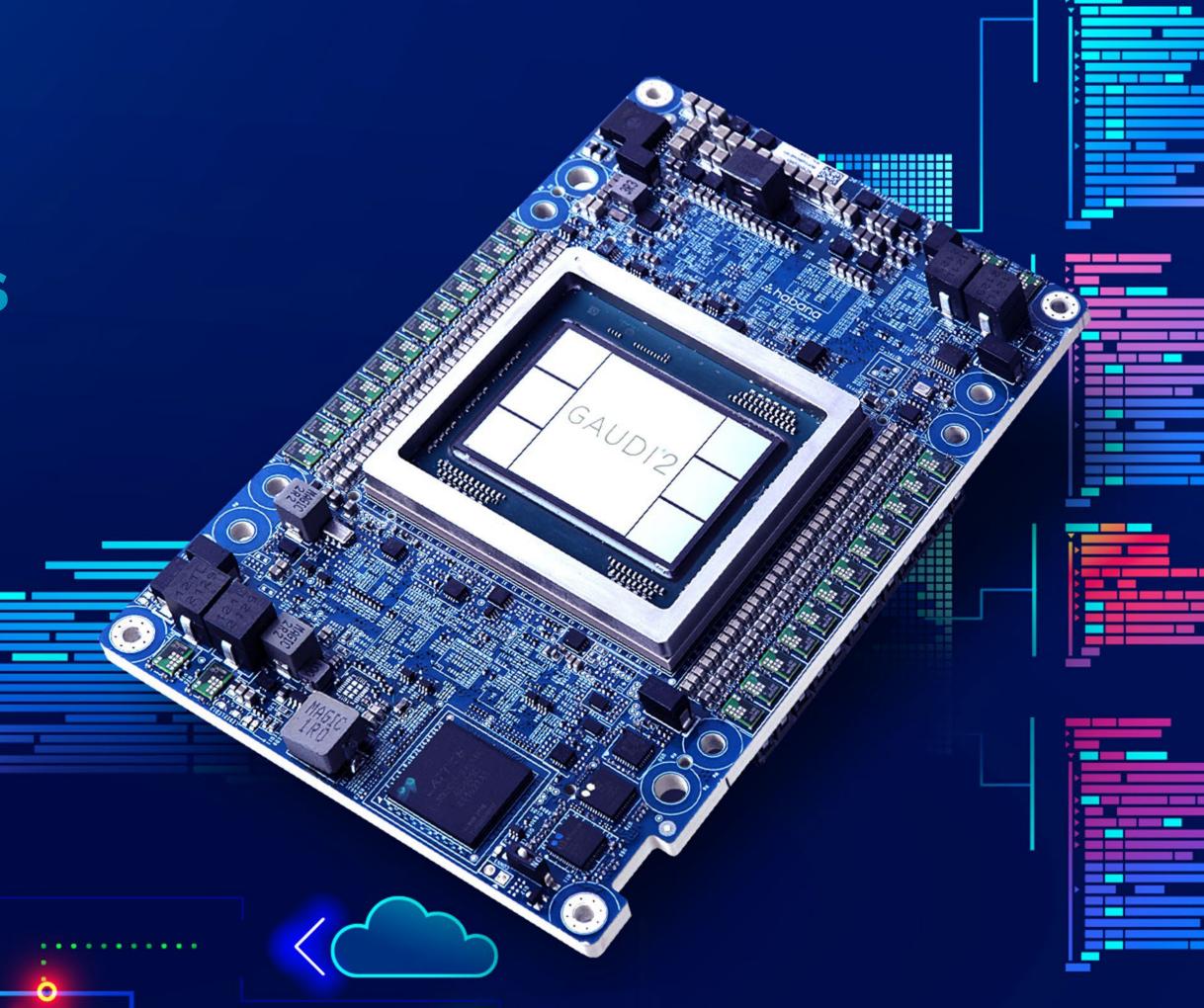
DEEP RENDER

Solving too much data and too little bandwidth problem using Intel Developer Cloud



Commitment to address every phase of the Al continuum

Performance metrics based on MLPerf Inference v3.1 benchmark. For configuration details, see the <u>results published by MLCommons</u>. Results may vary.





"Dell Technologies and Intel are collaborating to offer Al solutions to meet customers wherever they are on their Al journey. Combining the reliability of Dell PowerEdge servers – the industry's top selling portfolio – with Intel technologies for general purpose and accelerated compute provides powerful systems for optimized Al. PowerEdge systems with Xeon and Gaudi will support Al workloads ranging from large scale training to base level inferencing. We look forward to helping customers transform their business with new applications with this powerful combination."

Jeff Clarke

Vice Chairman and COO, Dell Technologies





intel。 XEON

4th Gen Intel® Xeon® Scalable Processor

MLPerf Al inference performance results: addressing every phase of the Al continuum

Performance metrics based on MLPerf Inference v3.1 benchmark. For configuration details, see the <u>results published by MLCommons</u>. Results may vary.

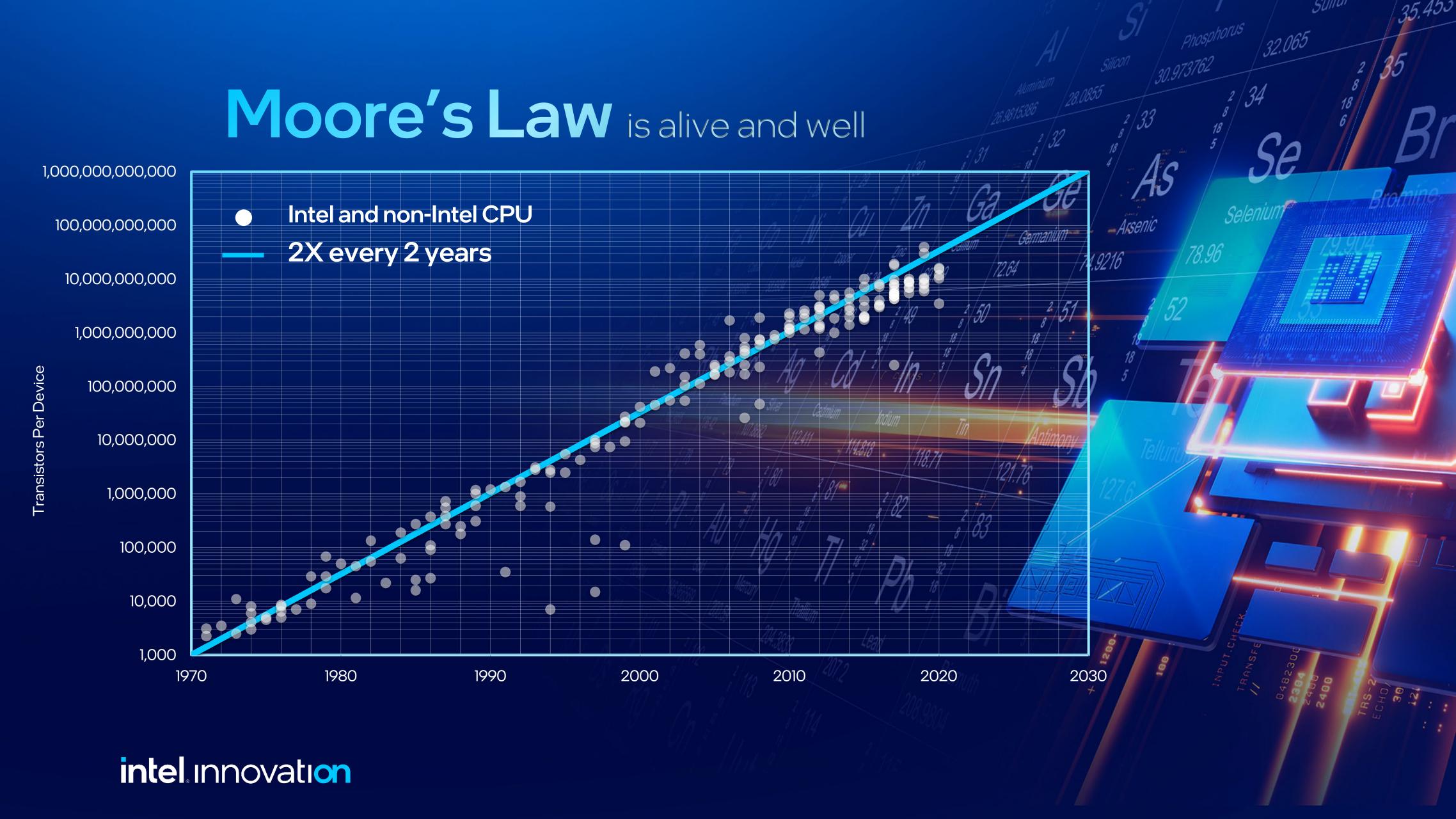


Alibaba.com















Using computational biology & gen Al

to dramatically speed up protein engineering process







AIPC

Fundamentally transforming the PC experience



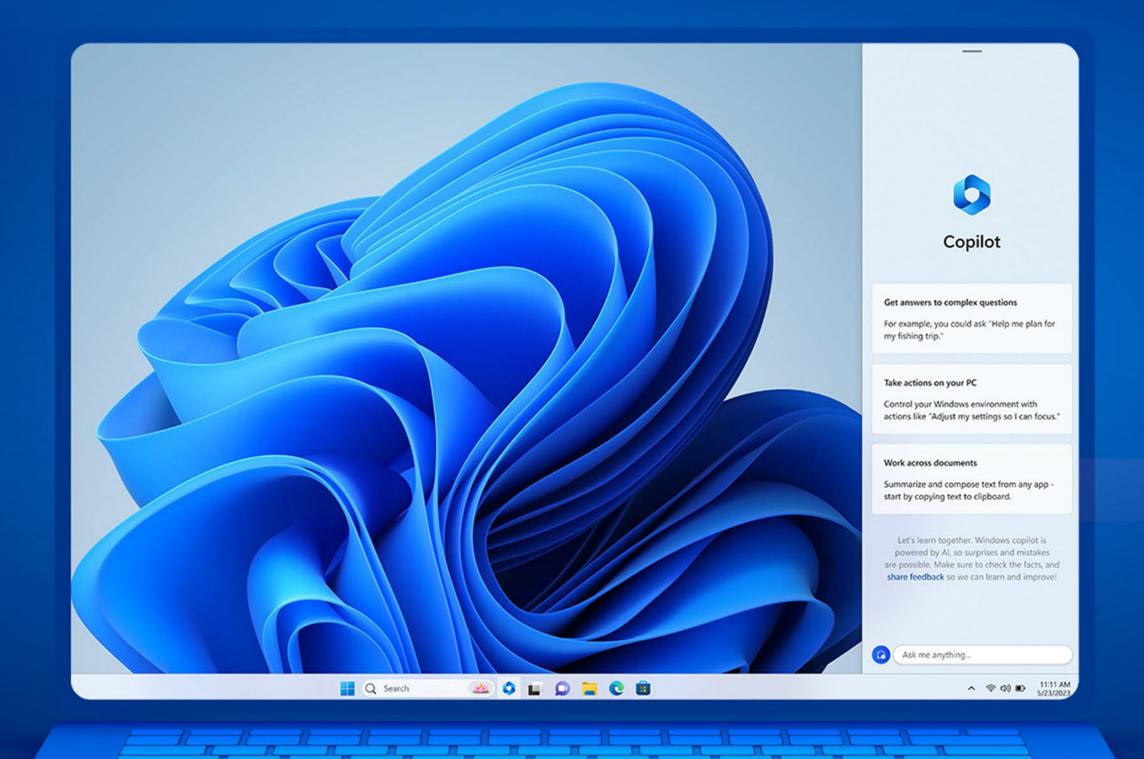








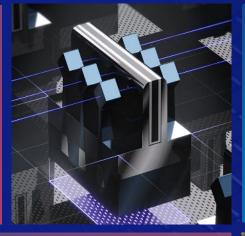
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First on Intel 4



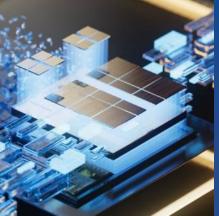
Using **EUV Technology**



Thunderbolt 4



3D Performance Hybrid Architecture



Built-In
NPU AI Engine

Low Power Island E-cores





Foveros
3D
Packaging

New P-core & E-core Microarchitecture

Built-in

intel

ARC



Latest **Media & Display**Standards

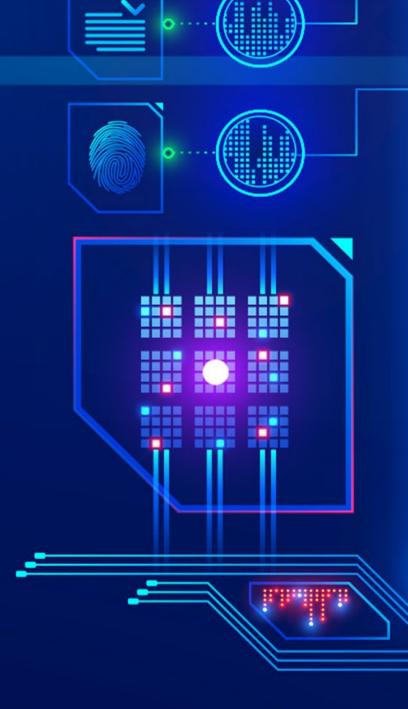






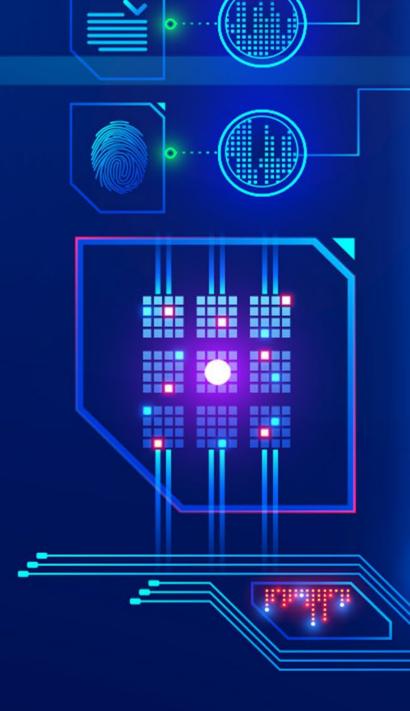
Jerry Kao

Chief Operating Officer, Acer









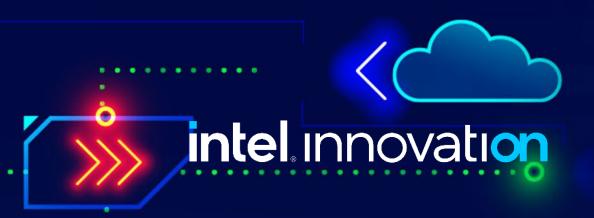




Performance per unit of energy

must become our industry's mission











Sierra Forest demo

2 processors with 288 cores

560 processor : 561 processor : 562 processor 563 processor : 564 processor : 565 processor : 566 processor : 567 processor : 568 processor : 569 processor 570 processor : 571 processor : 572 processor 573 processor : 574 processor : 575 processor demo@srfubuntu22p4-3405:~\$ intel

Xeon

288 COres Intel® Xeon® with E-core Launch 2024

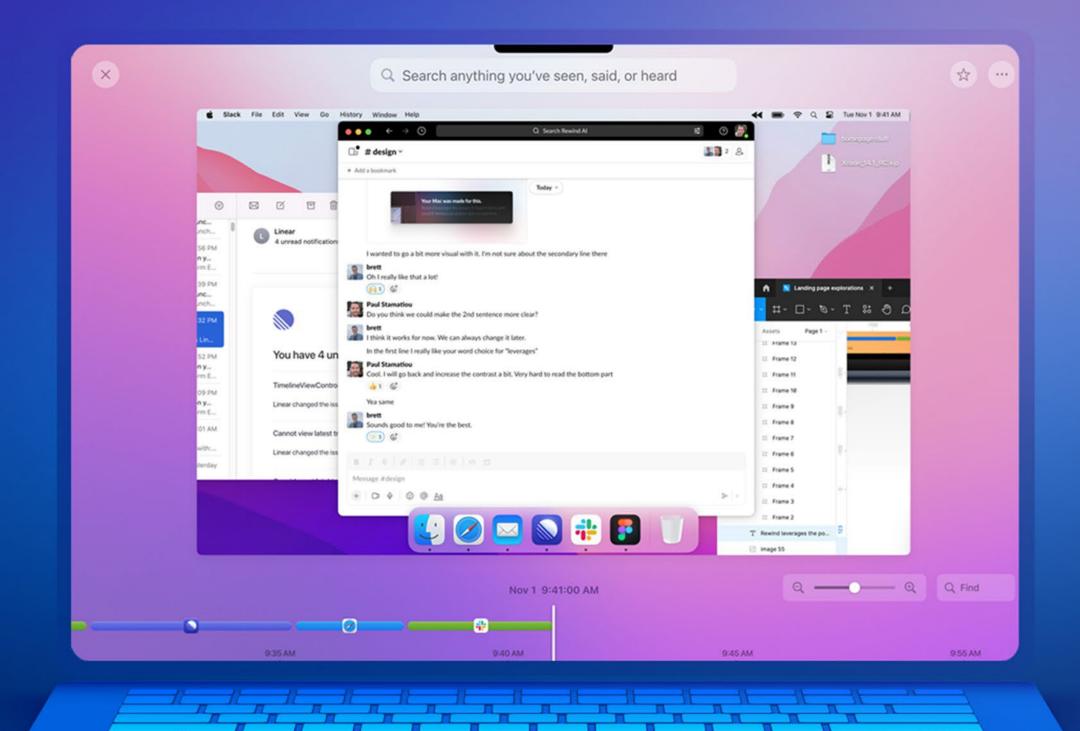






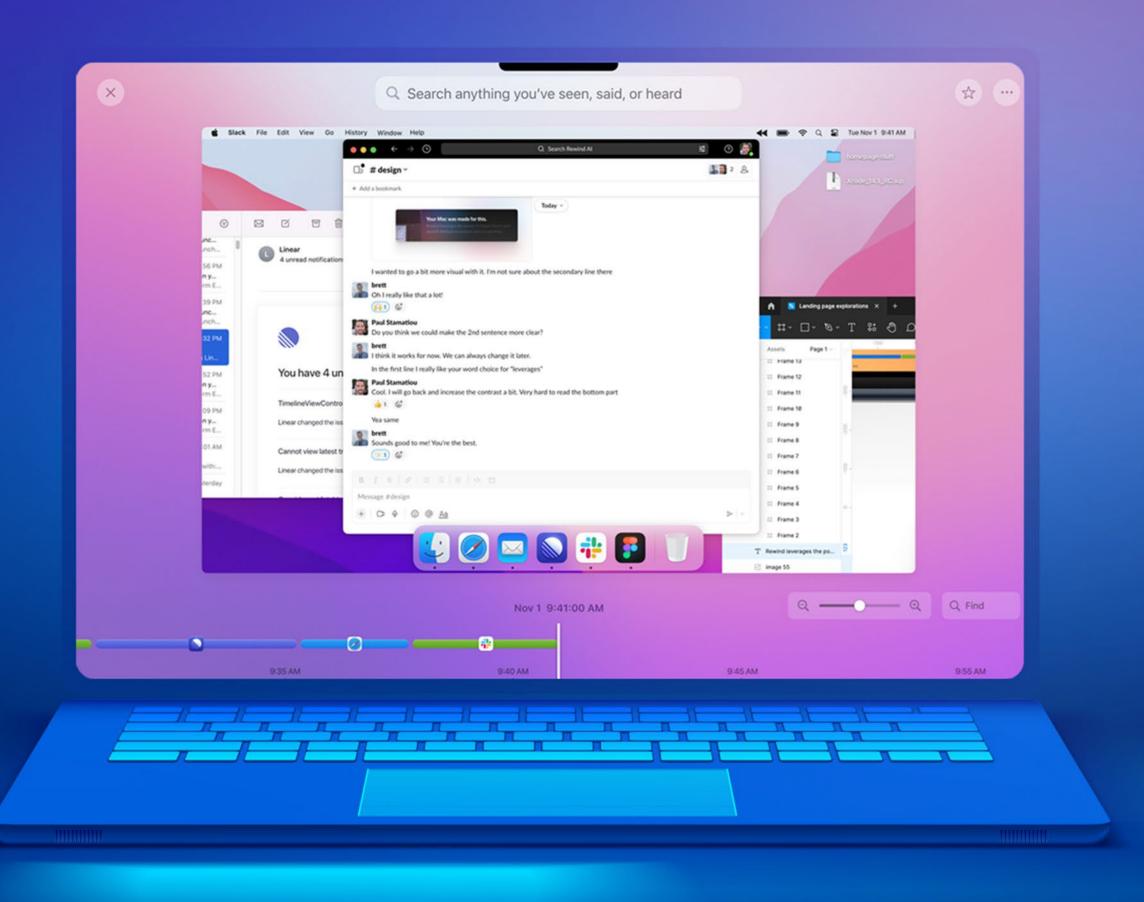
Rewind

Dan Siroker Founder of Rewind.ai

















Identified massive opportunity to democratize space & satellite tech ecosystem

OpenVINO

2023.

Al inferencing and deployment

Runtime of choice for developers on client and edge platforms

90%

Increase in OpenVINO Downloads since last year LLaMA
by 00 Meta

Optimizations to many of the GenAl models

Based on internal Intel data





intel_® + arm

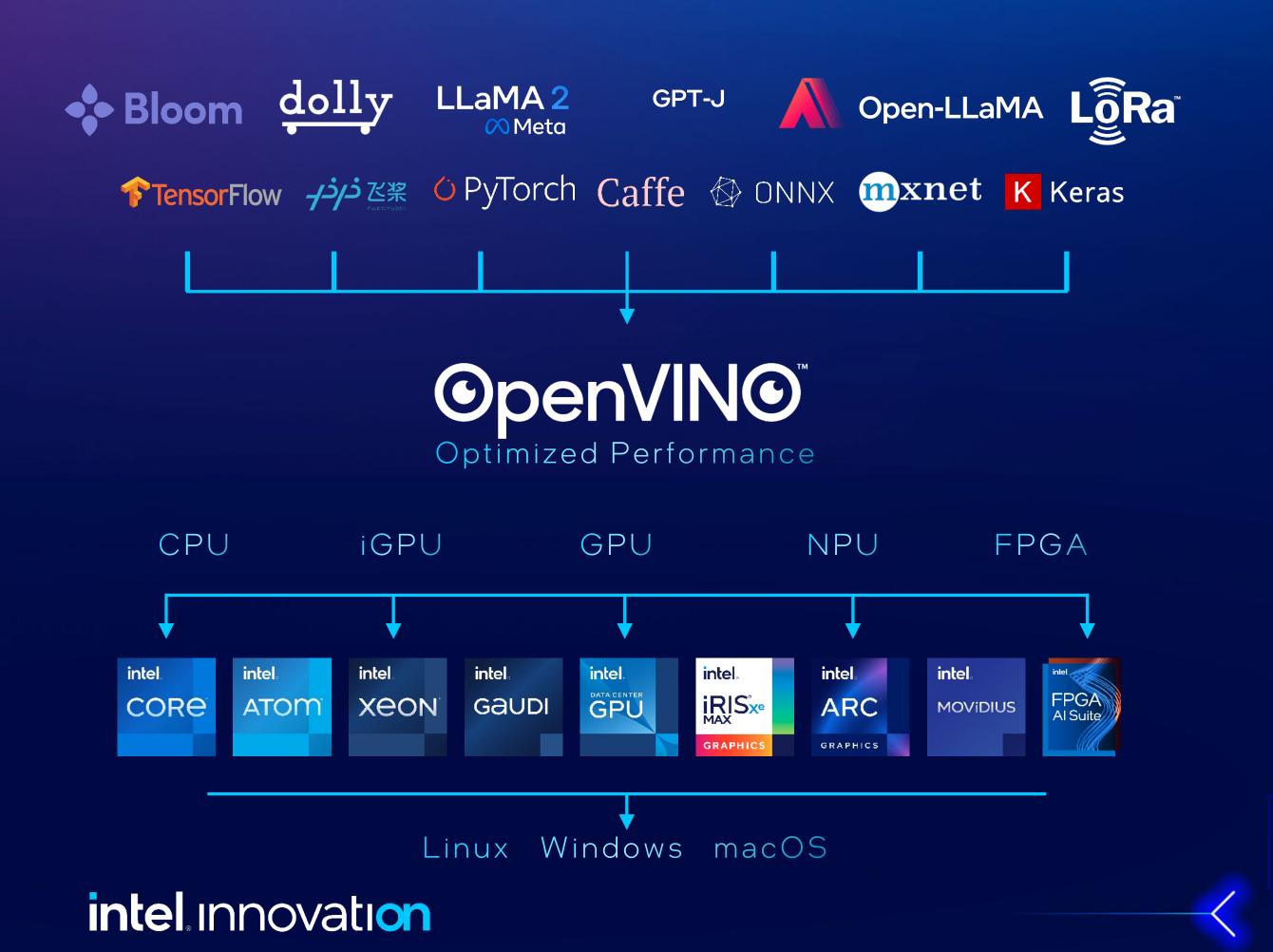
"Ensuring that developers have access to leading-edge tools and capabilities that allow them to write once and deploy anywhere is a key focus for Arm. We are pleased to see initiatives such as **OpenVINO** which specifically target the deployment of complex Al models to Arm CPUs and enable critical cross-platform support as more intelligent compute moves to the edge."

Dermot O'Driscoll

Vice President of Product Solutions, Infrastructure Line of Business, Arm



Yord A Enhancing performance and accessibility





Project Strata

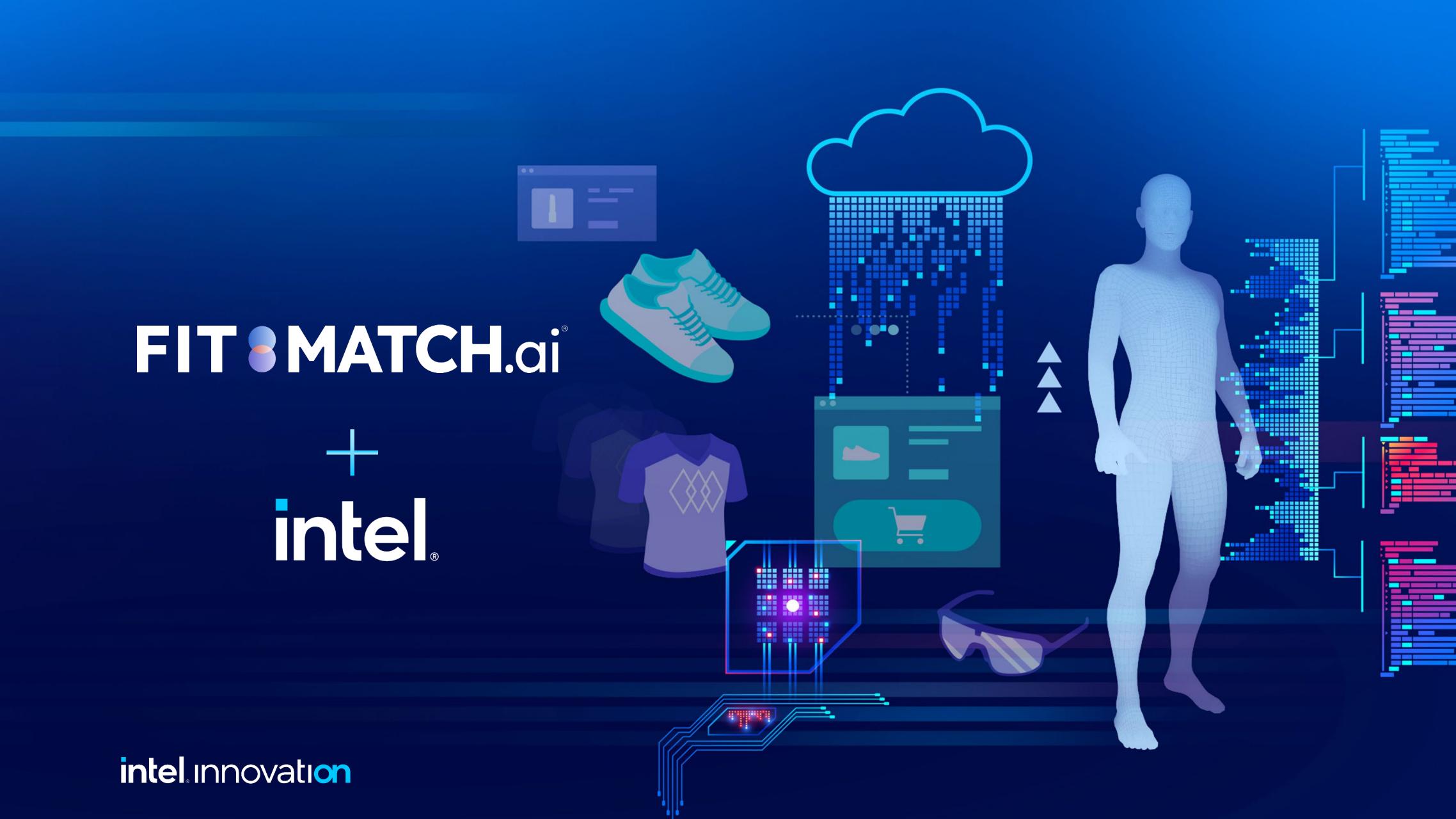
the development of a modular edge-native software platform that will accelerate the adoption of Al-Automation at the Edge

Observe

Orchestrate

Onboard





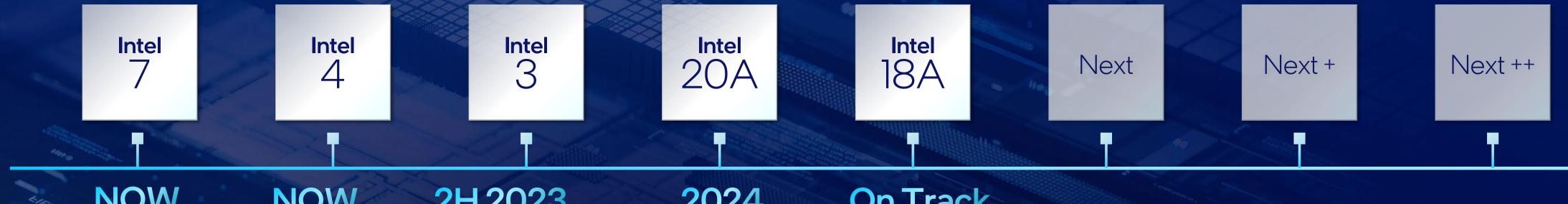
intel ignite

DEEP RENDER

Intel 2023 Startup Innovator

Award Winner

Beyond 5 Nodes in 4 Years Looking into the future today



NOW

In high volume manufacturing

NOW

High-volume ramp

2H 2023

Manufacturing ready, sampling Sierra Forest and Granite Rapids

2024

On-track for manufacturing

On Track

Silicon goes into the fab in Q12024

Release the 0.9 PDK to foundry customers

Test chips for multiple programs

Ribbon FET and PowerVia continuously evolving process technology

High-NA EUV technology development with 18A, production with "Intel Next"



Beyond 5 Nodes in 4 Years

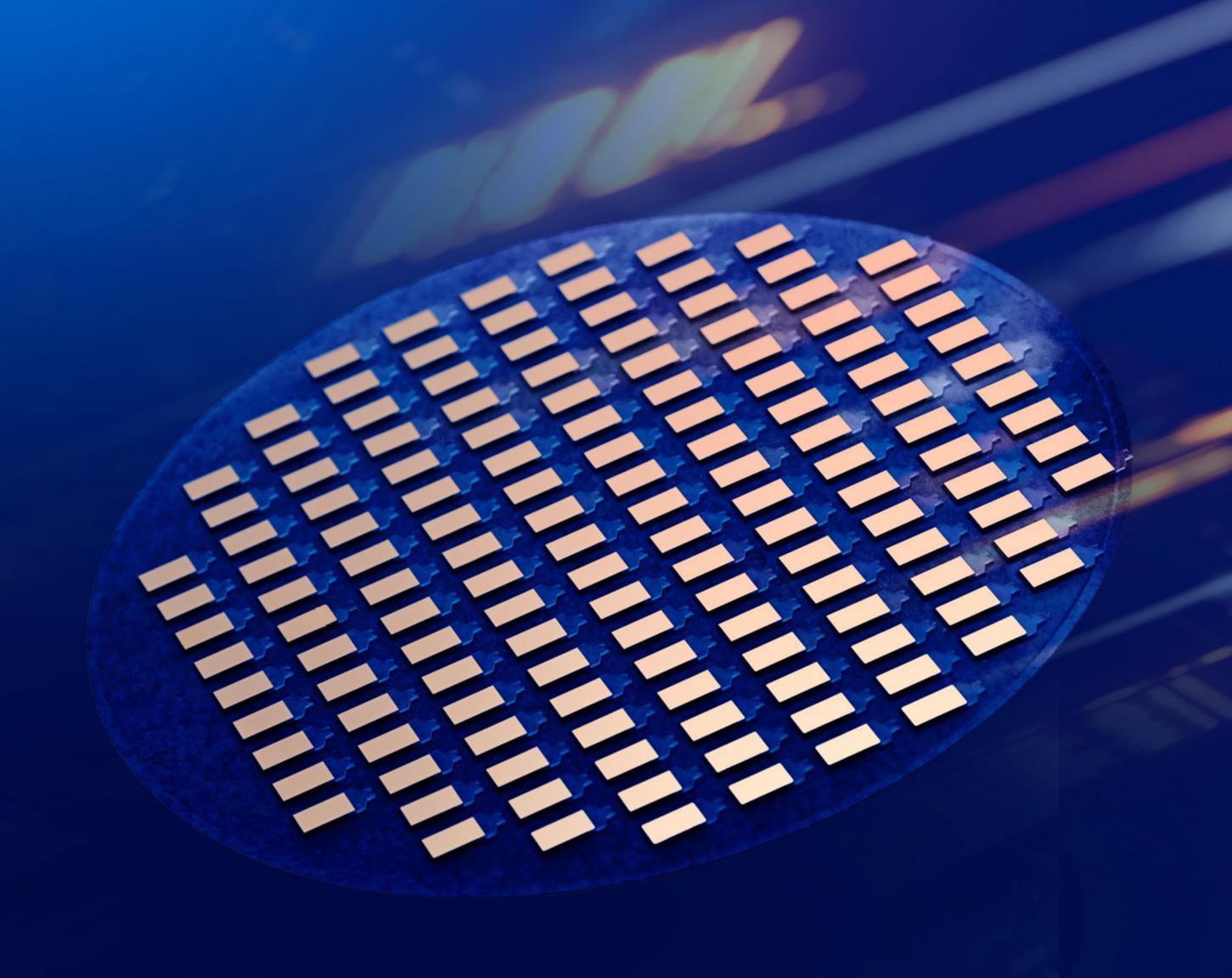
Looking into the future today



On Track
Silicon goes
into the fab in
Q1 2024

Advanced Packaging

Industry-first breakthroughs in glass substrates



\$100 Billion U.S. Investments



Oregon



Arizona



New Mexico



Ohio



EliuCle 120+ Members... Haiversal Chiplet 120+ and growing!

UCle™ Board Members





















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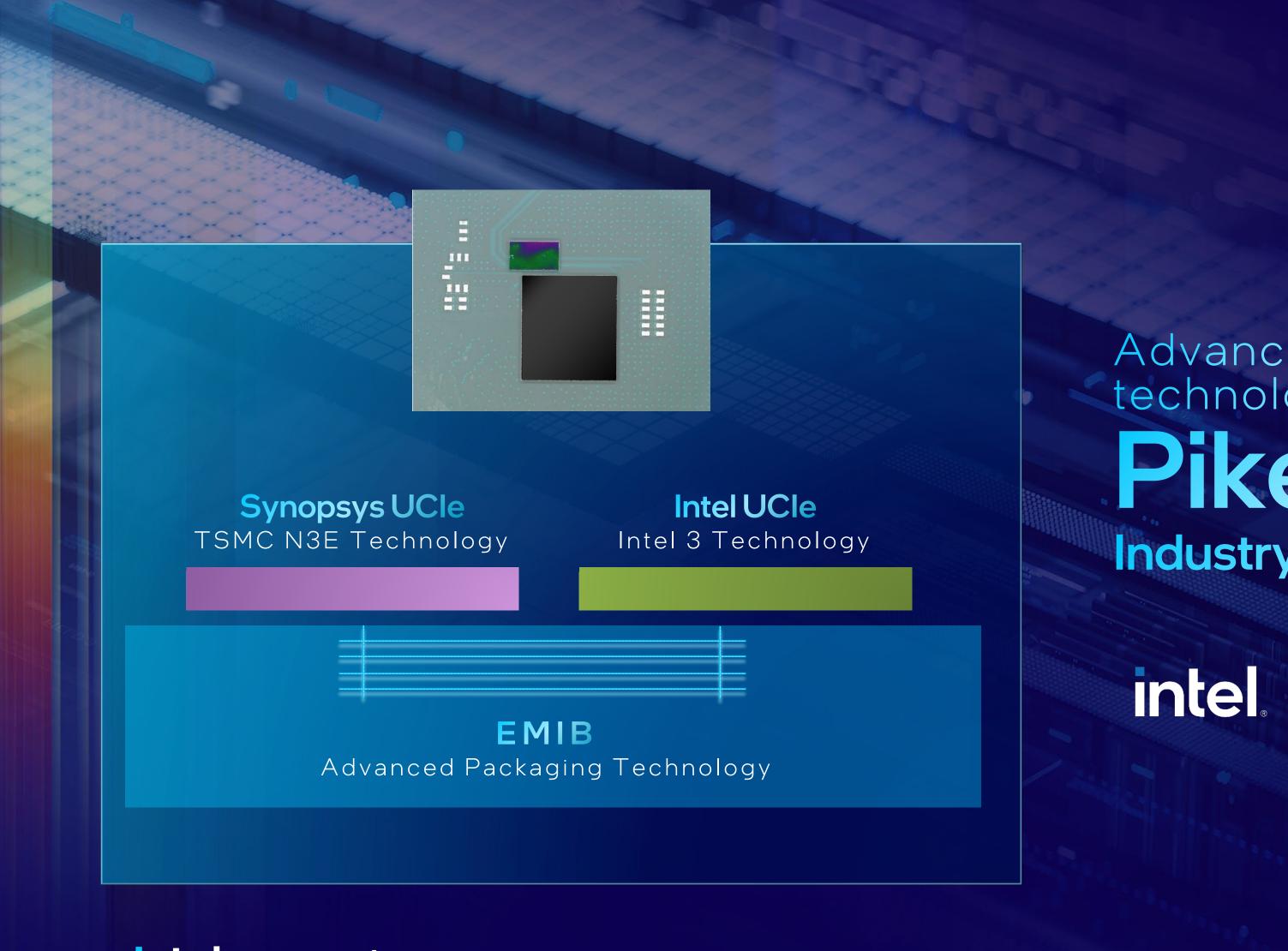
- Blue Cheetah
- Brite Semiconductor
- Broadcom
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- Credo
- Ecarx
- Eliyan
- Ericsson
- eTopus
- Futurewei Technologies
- Global Foundries
- Global Unichip Corporation
- Huixi Rhino
- IBM

- Imec
- Innosilicon
 - JCET
 - Juniper Networks
 - Keysight
 - Kiwimoore
 - LG
 - Lightmatter
 - M2 Semi
 - Macronix
 - Marvell
 - Mercedes-Benz

 - Microchip Micron
 - MediaTek

- National Institute of Advanced Industrial Science and Technology
- Neuron IP
- Physim
- Qualitas Semiconductor
- Point2Tech
- proteanTecs
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- Semitronix
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- Silicon Precision Industries
- SK Hynix
- SkyeChip
- Socionext

- Synopsys
- Tenstorrent
- Teradyne
- Tongfu Microelectronics
- Truechip
- University of New Hampshire InterOperability Laboratory
- Xi'an UnilC Semiconductors
- UNISOC
- Veri Silicon
- Winbond
- Xpeedic
- Zero ASIC
- Zentel



Advanced packaging technology codenamed

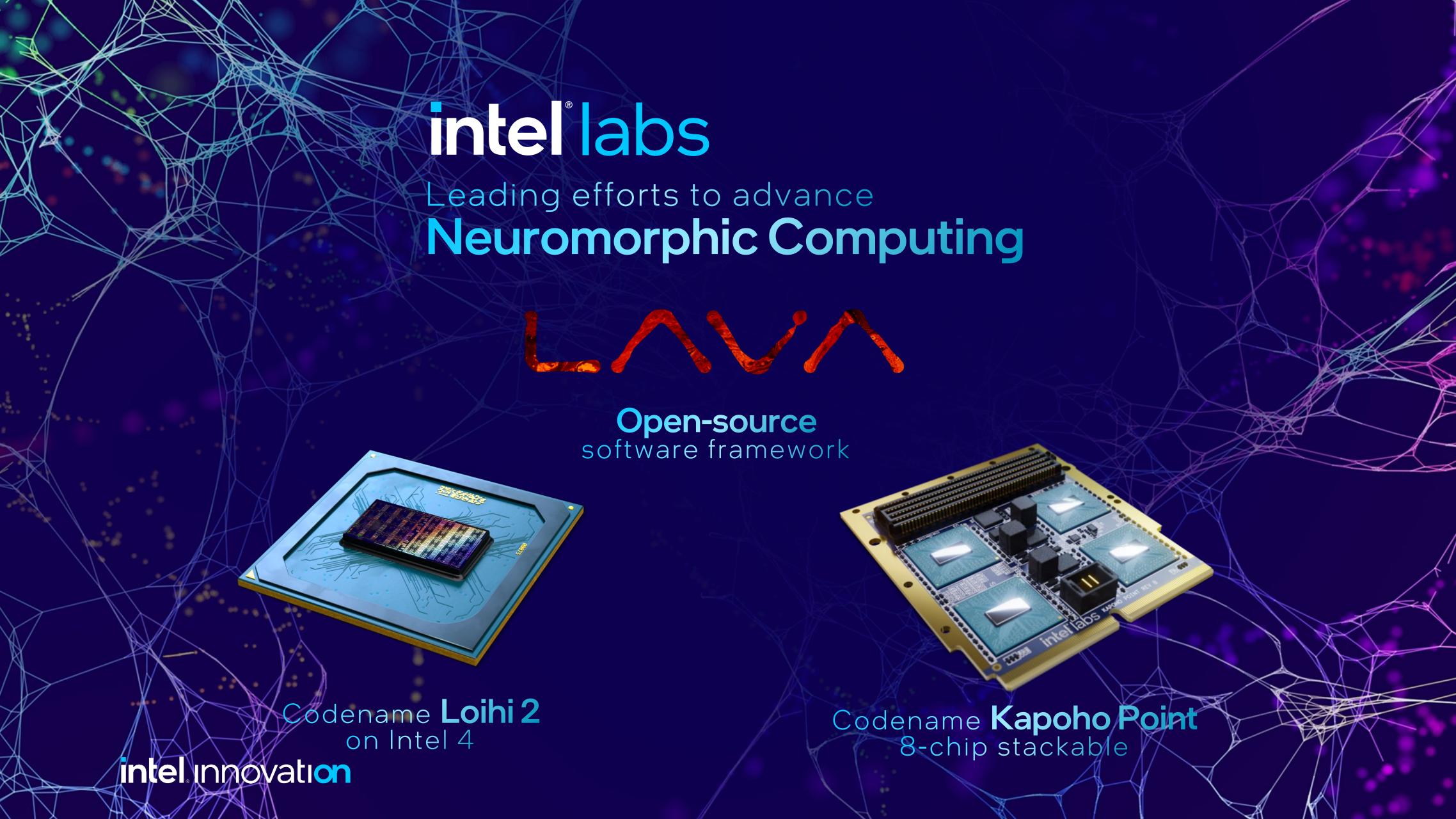
Pike Creek

Industry Interoperability Demo

intel synopsys®

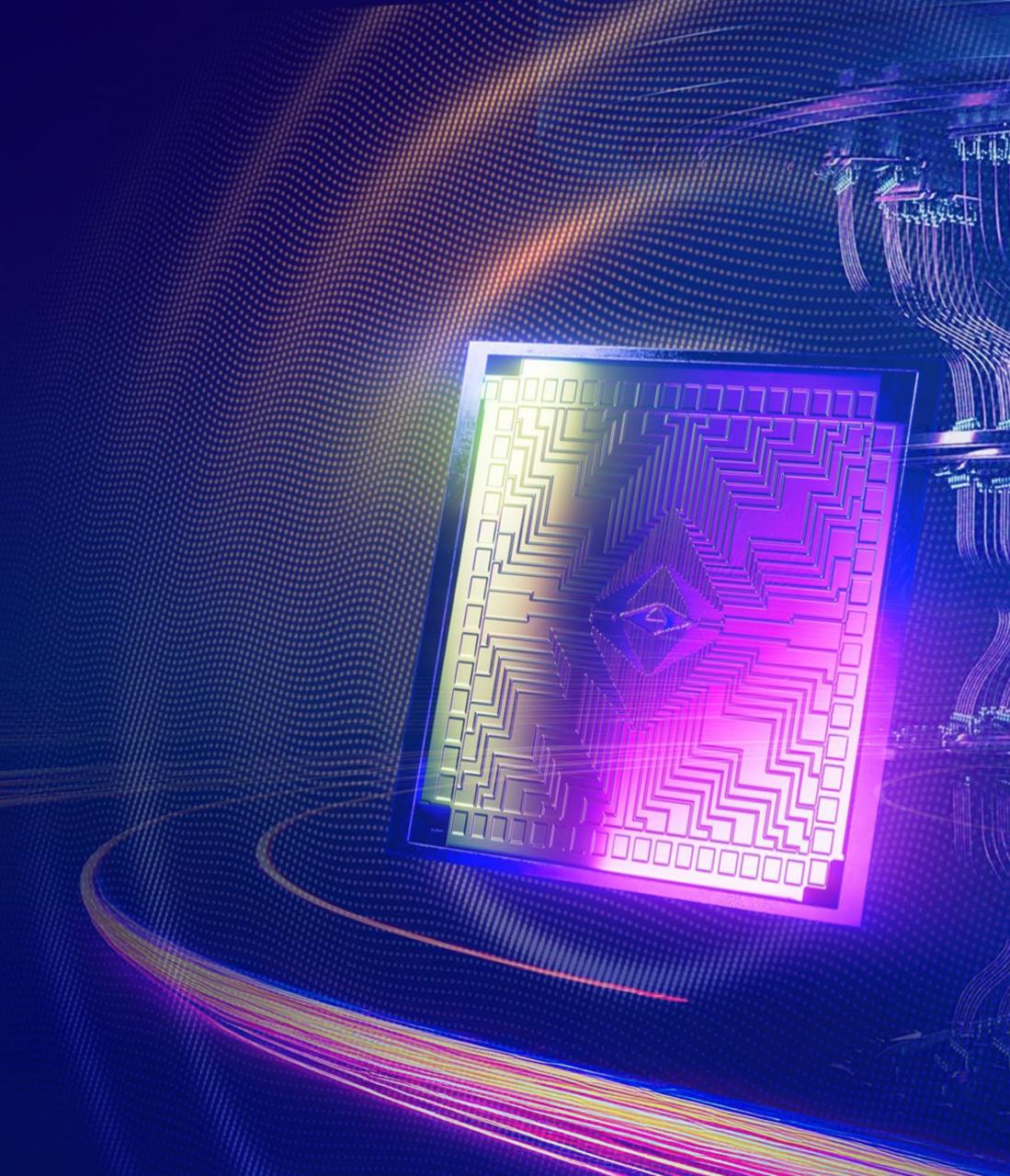


3-Dimensional Silicon Large Language Model computation needs the highest performance silicon **intel** innovation



Quantum

Harnessing the power of quantum physics to solve complex problems exponentially faster than large-scale supercomputers

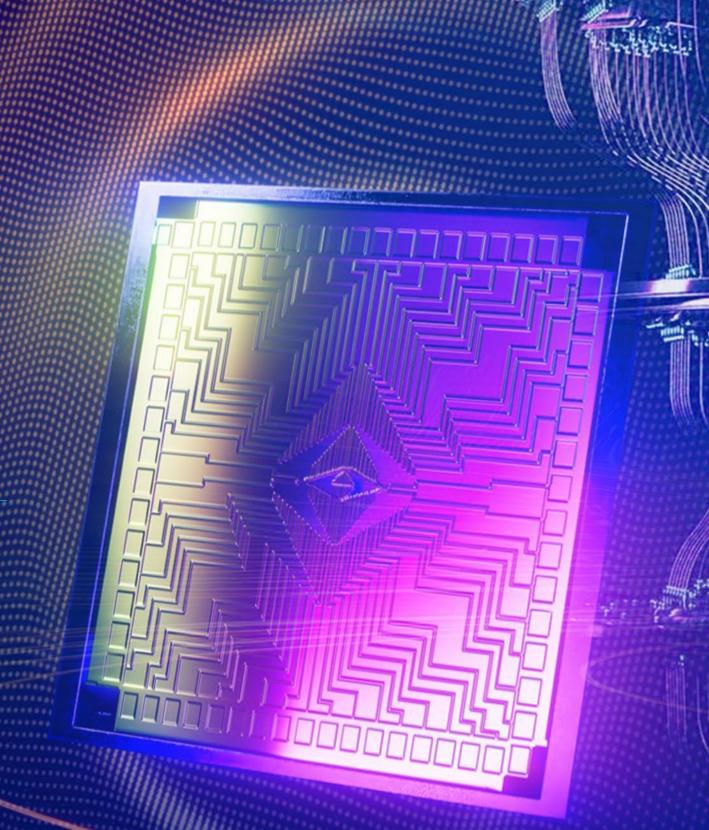


Intel quantum technology codenamed

Tunnel Falls

12 50x50 ~1 Million qubit device nanometers times smaller

95% Yield Rate across the wafer





Quantum Application

Quantum Compiler

Quantum Runtime

Quantum Control Simulator

Quantum Dot Simulator

Room Temperature Electronics

Cryogenic Control Chip

Spin Qubit Chip



Lifetime Achievement Award

Dr. Fei-Fei Li

Inaugural Sequoia Professor in the Computer Science Department at Stanford University, and Co-Director of Stanford's Human-Centered Al



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Exceptionally Engineered Al Platforms

Open & Hardware Agnostic
Software Approach

Confidently Trusted

Developing for the age of **AIPC**

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December 14, 2023



Launch of Intel® Core™ Ultra

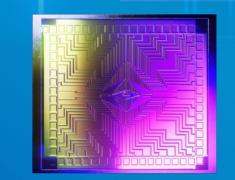


Launch of 5th Gen Intel® Xeon®

Advanced Packaging

Industry-first breakthroughs in glass substrates





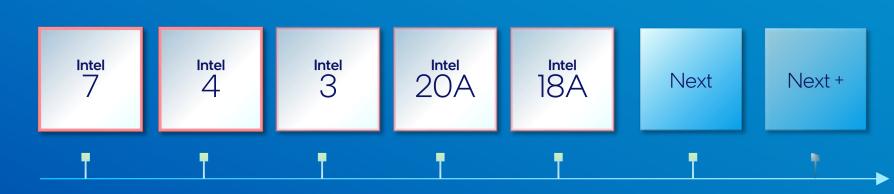
Quantum

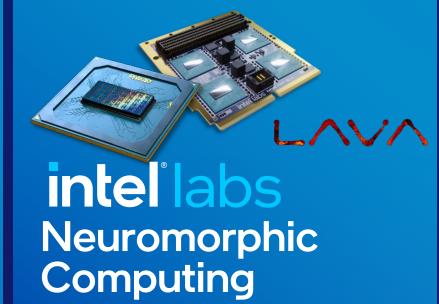
Innovating for the **future**



Beyond 5 Nodes in 4 Years

Looking into the future today







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intel_® Innovation

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